

# KPTD-1608ZGC

1.6 x 0.8 mm SMD Chip LED Lamp



# **DESCRIPTIONS**

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- . It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

## **FEATURES**

- 1.6 mm x 0.8 mm SMD LED, 0.95 mm thickness
- · Low power consumption
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

### **APPLICATIONS**

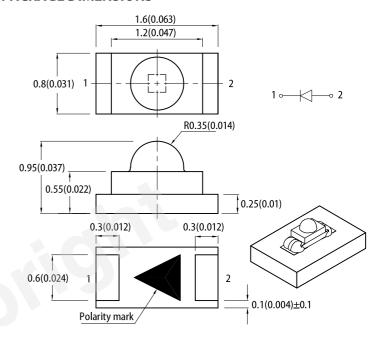
- Backlight
- Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

# **ATTENTION**

Observe precautions for handling electrostatic discharge sensitive devices

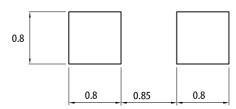


### **PACKAGE DIMENSIONS**



### **RECOMMENDED SOLDERING PATTERN**

(units: mm; tolerance: ± 0.1)



- Tolerance is ±0.15(0.006") unless otherwise noted.

  The specifications, characteristics and technical data described in the datasheet are subject to The specifications, characte change without prior notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.

# **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]
			Min.	Тур.	201/2
KPTD-1608ZGC	Green (InGaN)	Water Clear	700	1300	60°

Notes.

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.





# ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Parameter		Emitting Color	Тур.	Max.	Unit
Wavelength at Peak Emission I <sub>F</sub> = 20mA	$\lambda_{peak}$	Green	515	-	nm
Dominant Wavelength I <sub>F</sub> = 20mA	λ <sub>dom</sub> <sup>[1]</sup>	Green	525	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX I <sub>F</sub> = 20mA	Δλ	Green	30	-	nm
Capacitance	С	Green	45	-	pF
Forward Voltage I <sub>F</sub> = 20mA	V <sub>F</sub> <sup>[2]</sup>	Green	3.3	4.1	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Green	-	50	μΑ
Temperature Coefficient of $\lambda_{\text{peak}}$ $I_F$ = 20mA, -10°C $\leq T \leq 85^{\circ}C$	TC <sub>λpeak</sub>	Green	0.05	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F$ = 20mA, -10°C $\leq T \leq 85^{\circ}C$	TC <sub>Adom</sub>	Green	0.03	-	nm/°C
Temperature Coefficient of $V_F$ $I_F$ = 20mA, -10°C $\leq$ T $\leq$ 85°C	TC <sub>V</sub>	Green	-2.8	-	mV/°C

### Notes:

# ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	102.5	mW
Reverse Voltage	V <sub>R</sub>	5	V
Junction Temperature	Tj	115	°C
Operating Temperature	T <sub>op</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-40 to +85	°C
DC Forward Current	I <sub>F</sub>	25	mA
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	150	mA
Electrostatic Discharge Threshold (HBM)	-	450	V
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	460	°C/W
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	325	°C/W

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. R<sub>In. Ja.</sub> R<sub>In. Ja.</sub> Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



Notes.

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)

2. Forward voltage: ±0.1V.

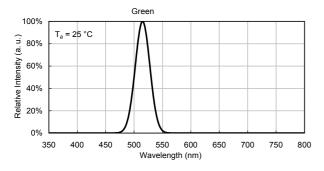
3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

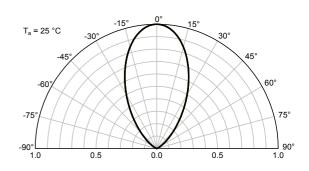


## **TECHNICAL DATA**

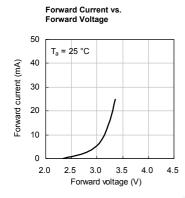
### **RELATIVE INTENSITY vs. WAVELENGTH**

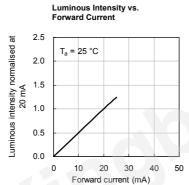


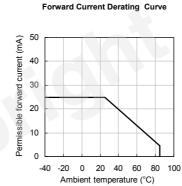
# **SPATIAL DISTRIBUTION**

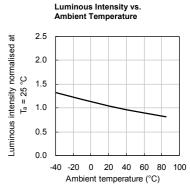


# **GREEN**

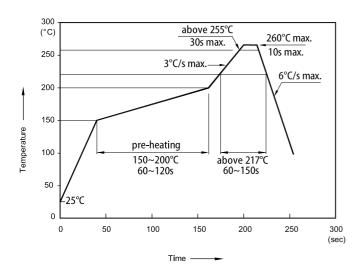








### REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



### Notes:

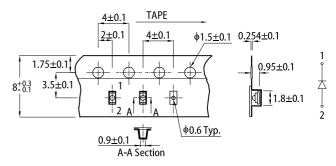
- Notes.

  1. Don't cause stress to the LEDs while it is exposed to high temperature.

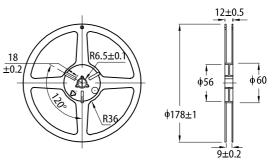
  2. The maximum number of reflow soldering passes is 2 times.

  3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product

### TAPE SPECIFICATIONS (units:mm)

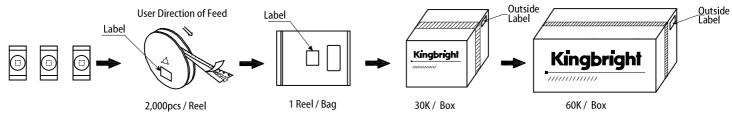


# **REEL DIMENSION** (units: mm)





## **PACKING & LABEL SPECIFICATIONS**





- PRECAUTIONARY NOTES

  1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.

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